



3D Plus October 2009, 20th
New DDR2 SDRAM Memory Family

- 4Gb up to 8Gb total capacity
- x4, x8 or x16 organization
- Ball Grid Array package (63, 65, 87 solder balls)
- Clock Speed : 400, 533 and 667 Mbps
- Commercial and Extended temperature range
- Full Lead Free (Tin Lead solderball available)



Leading company in the field of high density stacked memories, **3D Plus** is introducing a new component-off-the-shelf DDR2 SDRAM Family.

3D Plus excellence and innovation are applied to new standard product developments suitable for harsh environments such as SRAM, Flash, E2Prom, SDRam, DDR2 and DDR3.

Its technology provides high density memory configurations fully JEDEC compliant. It makes our products suitable for memory module manufacturers, workstation, server and networking / communication applications, data storage as well as high performance and harsh environments embedded systems.

Due to its high reliability proven technology, these components meet very well requests of defense & security markets and more generally all HiRel markets.

All documents can be downloaded from [here](#).

Don't hesitate to [contact us](#) or our [Sales Network Representatives](#) for any complementary information you would need.

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